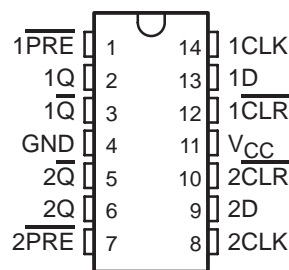


# DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCAS499A – DECEMBER 1986 – REVISED APRIL 1996

- Center-Pin  $V_{CC}$  and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1- $\mu$ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (D) and Thin Shrink Small-Outline (PW) Packages, and Standard Plastic 300-mil DIPs (N)

D, N, OR PW PACKAGE  
(TOP VIEW)

## description

This device contains two independent positive-edge-triggered D-type flip-flops. A low level at the preset ( $\overline{PRE}$ ) or clear ( $\overline{CLR}$ ) input sets or resets the outputs regardless of the levels of the other inputs. When  $\overline{PRE}$  and  $\overline{CLR}$  are inactive (high), data at the data (D) input that meets the setup-time requirements are transferred to the outputs on the low-to-high transition of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

The 74AC11074 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

FUNCTION TABLE

INPUTS				OUTPUT	
$\overline{PRE}$	$\overline{CLR}$	CLK	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H <sup>†</sup>	H <sup>†</sup>
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	$Q_0$	$\overline{Q}_0$

<sup>†</sup> This configuration is nonstable; that is, it does not persist when  $\overline{PRE}$  or  $\overline{CLR}$  returns to its inactive (high) level.



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 **TEXAS  
INSTRUMENTS**

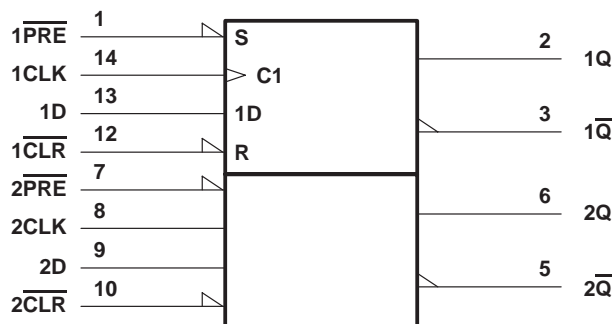
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# 74AC11074 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 50$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 100$ mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2):	
D package .....	1.25 W
N package .....	1.1 W
PW package .....	0.5 W
Storage temperature range, $T_{stg}$ .....	$-65^\circ\text{C}$ to $150^\circ\text{C}$

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The maximum package power dissipation is calculated using a junction temperature of  $150^\circ\text{C}$  and a board trace length of 750 mils, except for the N package, which has a trace length of zero.



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**recommended operating conditions**

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	3	5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
		V <sub>CC</sub> = 4.5 V	3.15		
		V <sub>CC</sub> = 5.5 V	3.85		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 3 V	0.9		V
		V <sub>CC</sub> = 4.5 V	1.35		
		V <sub>CC</sub> = 5.5 V	1.65		
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>		V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>		V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V	-4		mA
		V <sub>CC</sub> = 4.5 V	-24		
		V <sub>CC</sub> = 5.5 V	-24		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V	12		mA
		V <sub>CC</sub> = 4.5 V	24		
		V <sub>CC</sub> = 5.5 V	24		
Δt/Δv	Input transition rise or fall rate	0	10		ns/V
T <sub>A</sub>	Operating free-air temperature	-40	85		°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		
		4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
		5.5 V	I <sub>OH</sub> = -75 mA <sup>†</sup>			3.85		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V				0.1		V
		4.5 V				0.1		
		5.5 V				0.1		
	I <sub>OL</sub> = 12 mA	3 V				0.36		
		4.5 V				0.36		
		5.5 V				0.36		
		5.5 V	I <sub>OL</sub> = 75 mA <sup>†</sup>			1.65		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V				±0.1	±1	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V				4	40	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V	3.5					pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



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## DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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timing requirements over recommended operating free-air temperature range,  
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (see Figure 1)

		$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
		MIN	MAX			
$f_{\text{clock}}$	Clock frequency	0	100	0	100	MHz
$t_w$	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	4	4	ns	
		CLK low or high	5	5		
$t_{\text{su}}$	Setup time before CLK $\uparrow$	Data high or low	5	5	ns	
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	1	1		
$t_h$	Hold time after CLK $\uparrow$	0	0	0	ns	

timing requirements over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (see Figure 1)

		$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
		MIN	MAX			
$f_{\text{clock}}$	Clock frequency	0	125	0	125	MHz
$t_w$	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	4	4	ns	
		CLK low or CLK high	4	4		
$t_{\text{su}}$	Setup time before CLK $\uparrow$	Data high or low	3.5	3.5	ns	
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	1	1		
$t_h$	Hold time after CLK $\uparrow$	0	0	0	ns	

switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
$f_{\text{max}}$			100	125		100		MHz
$t_{\text{PLH}}$	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$	1.5	5.8	9.3	1.5	10	ns
$t_{\text{PHL}}$			1.5	6.5	11.4	1.5	12.2	
$t_{\text{PLH}}$	CLK	Q or $\overline{\text{Q}}$	1.5	7.7	10.5	1.5	11.3	ns
$t_{\text{PHL}}$			1.5	7.3	9.7	1.5	10.6	

switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
$f_{\text{max}}$			125	150		125		MHz
$t_{\text{PLH}}$	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$	1.5	4.2	6.6	1.5	7.1	ns
$t_{\text{PHL}}$			1.5	4.7	8.2	1.5	9	
$t_{\text{PLH}}$	CLK	Q or $\overline{\text{Q}}$	1.5	5.4	7.5	1.5	8.2	ns
$t_{\text{PHL}}$			1.5	5	6.9	1.5	7.5	

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

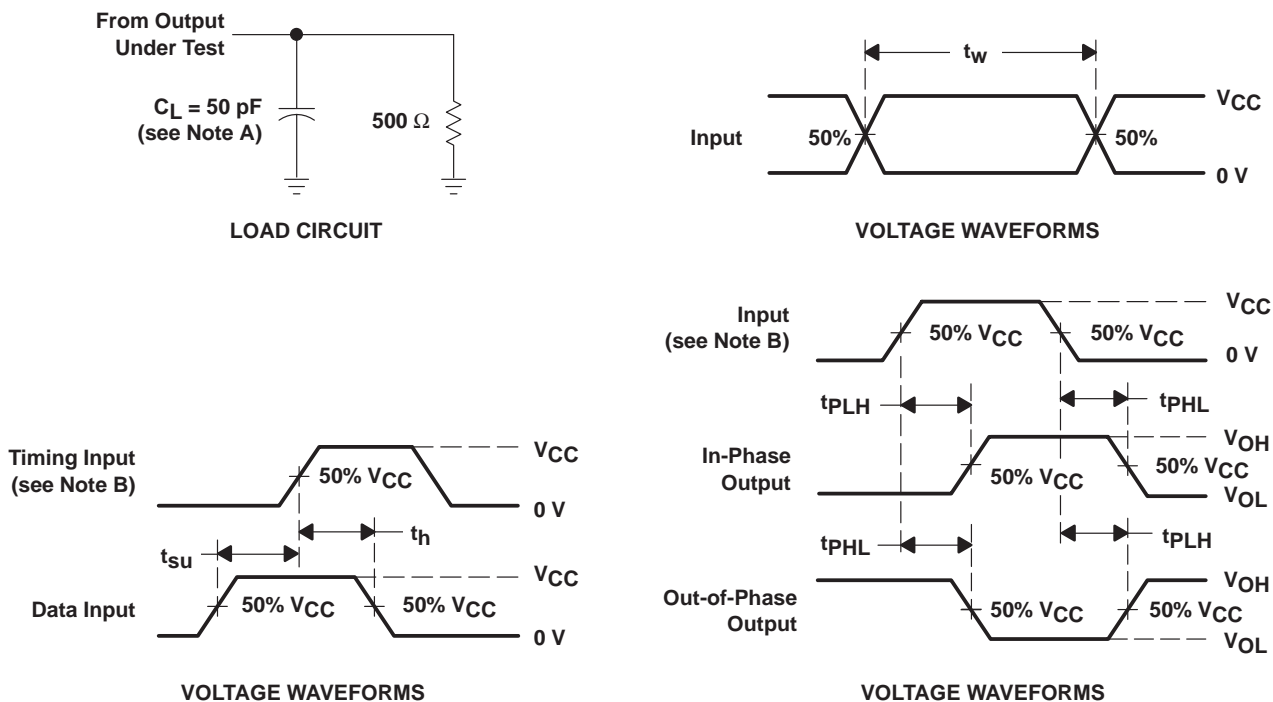
PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{\text{pd}}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	30	pF



**74AC11074**  
**DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP**  
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**PARAMETER MEASUREMENT INFORMATION**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .  
 C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AC11074D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11074NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11074PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
74AC11074PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC11074DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
74AC11074PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC11074DR	SOIC	D	14	2500	367.0	367.0	38.0
74AC11074PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

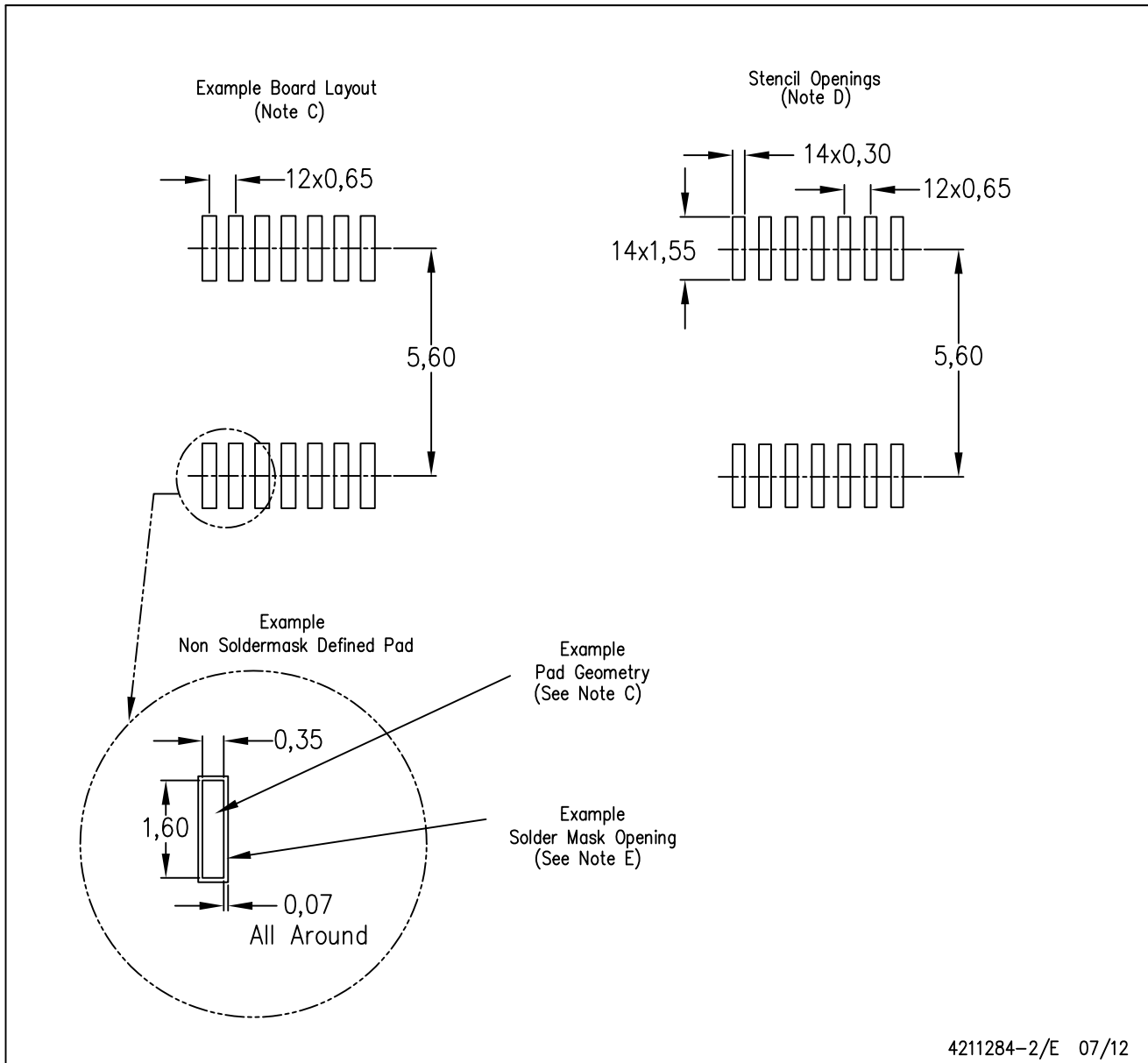


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- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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